



2.5A SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER

FEATURES:

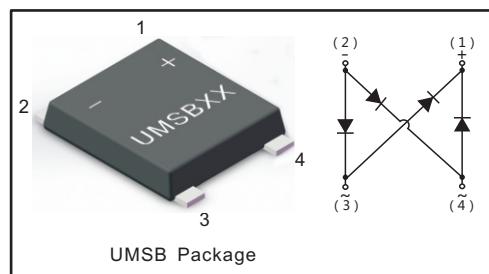
- Glass Passivated Chip Junction
- Reverse Voltage - 800 to 1000 V
- Forward Current - 2.5 A
- Fast reverse recovery time
- Designed for Surface Mount Application

PINNING

PIN	DESCRIPTION
1	Output Anode (+)
2	Output Cathode (-)
3	Input Pin (~)
4	Input Pin (~)

MECHANICAL DATA

- Case: UMSB
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 0.234g / 0.00825oz



Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

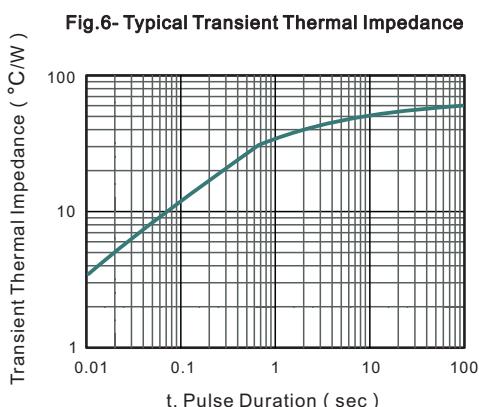
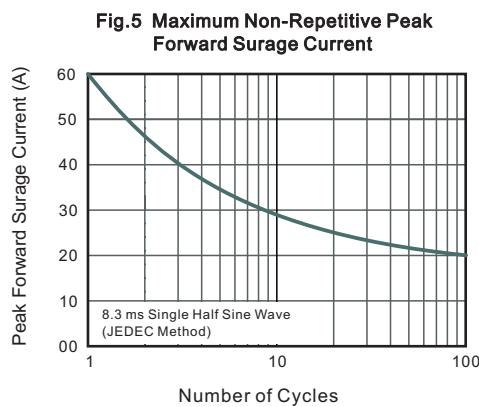
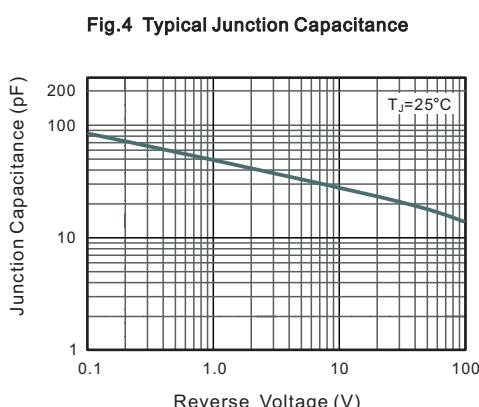
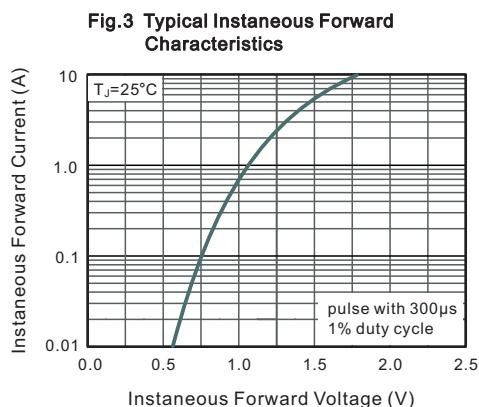
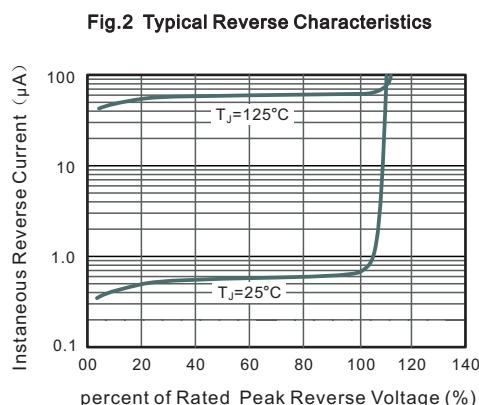
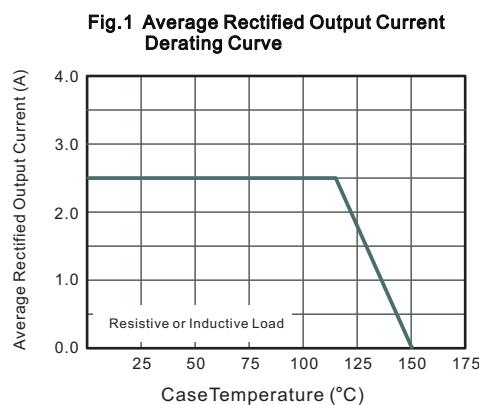
Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	FMSB25K	FMSB25M	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	800	1000	V
Maximum RMS voltage	V_{RMS}	560	700	V
Maximum DC Blocking Voltage	V_{DC}	800	1000	V
Average Rectified Output Current at $T_c = 115^\circ C$	I_o	2.5		
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	60		
Maximum Forward Voltage at 2.5 A	V_F	1.3		
Maximum DC Reverse Current $T_a = 25^\circ C$ at Rated DC Blocking Voltage $T_a = 125^\circ C$	I_R	5 200		
Typical Junction Capacitance (Note1)	C_j	35		
Typical Thermal Resistance (Note2)	$R_{\theta JA}$ $R_{\theta JA}$ $R_{\theta JA}$	60 15 25		
Maximum Reverse Recovery Time (Note3)	t_{rr}	500		
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150		

Note:1. Measured at 1 MHz and applied reverse voltage of 4 V D.C

2. Mounted on glass epoxy PC board with 4×1.5"×1.5" (3.81×3.81 cm) copper pad.

3. Measured with $I_F = 0.5 A$, $I_R = 1 A$, $I_{rr} = 0.25 A$.

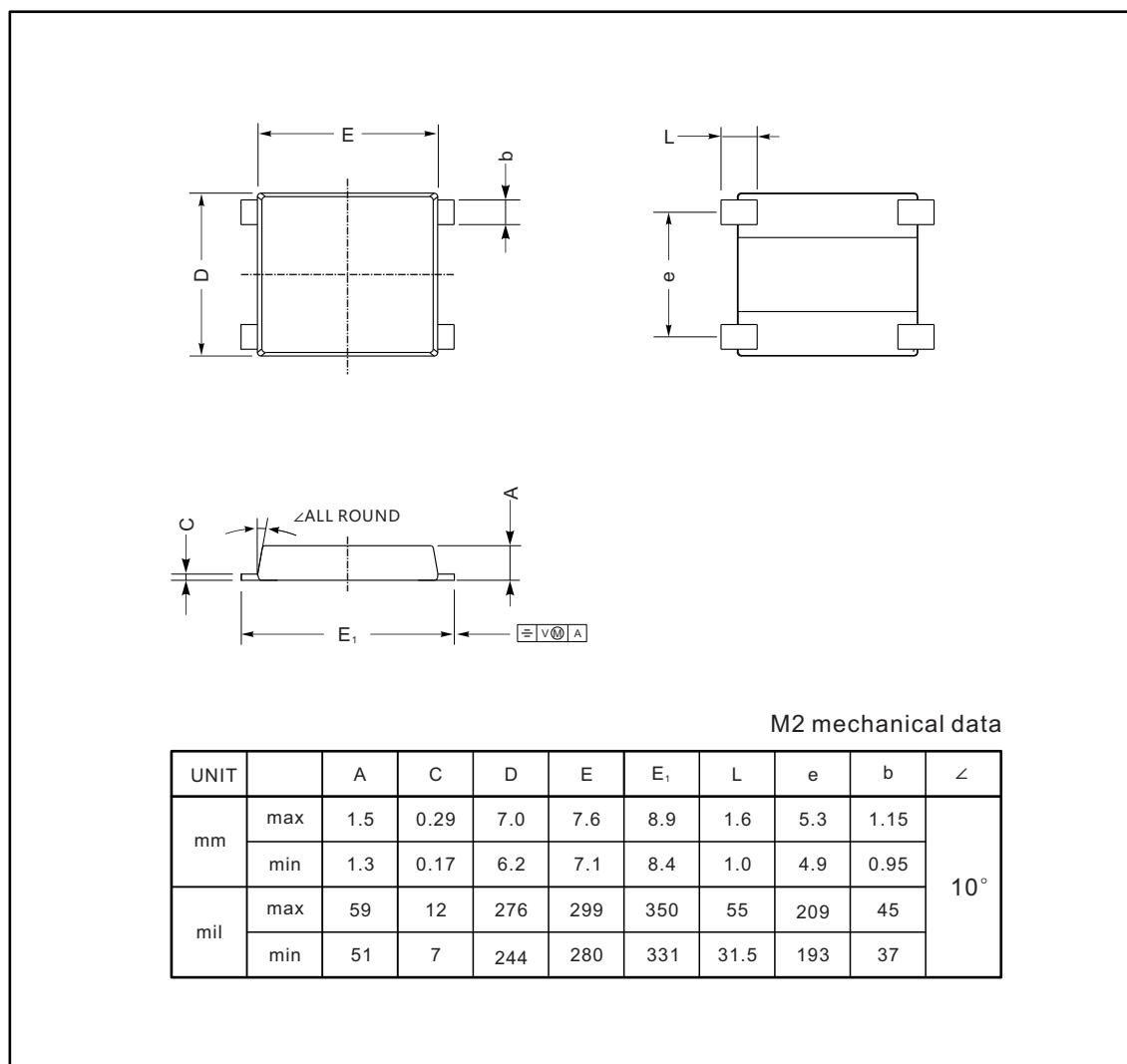




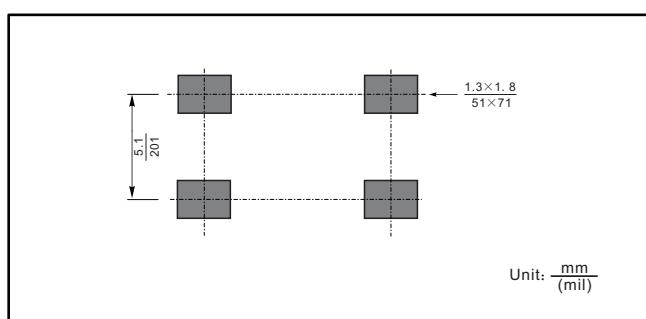
PACKAGE OUTLINE

Plastic surface mounted package; 4 leads

UMSB



The recommended mounting pad size



Marking

Type number	Marking code
FMSB25K	FMB25K
FMSB25M	FMB25M